Form Revision: 07/30/19

Customer Application Requirements

LPMS
USA

Please, fill out this form and send to sales@lpms-usa.com, and an LPMS USA representative will contact you with a recommendation.

Customer Information

Company name	Contact name
Phone Number	Email Address
Ship to / manufacturing address	Project coordinator and title (and location if different than ship to address)
Engineering contact (and location if different than ship to address)	If this is your first RFQ to LPMS, how did you find out about LPMS USA?

Why was LPM considered (e.g., what is important for this application)?

How did you hear about LPMS USA?

Can we share your information with our partner LPMS International?

Commercial Information

Description or name of your application/code name:

New or existing product? And when will pc boards or cables be available?

Quantity of prototype parts needed? When?

Quantity of production parts needed per year? When does production start?

Product Specifics

Product size? Rough estimates are fine for costing if CAD is not available.

Drawings or CAD available for part to be encapsulated?

*Initial costing will be more accurate with CAD data. If CAD data is available, please provide STEP files.
Either way, costing assumes 3d STEP or ProE/Creo files for pcb and/or cable accompany tooling PO.*

Harness or cable strain relief features or requirements?

Molded logo or molded number requirements?

Aesthetic requirements

(e.g., EDM finish is standard for production tooling).

Do you prefer one shot of encapsulation material OR complete coverage of the part to be encapsulated with two shots?

If you request more than one shot, please describe specifics (e.g., 1st shot of amber with 2nd shot of black). FYI - with one shot, the tooling will need to hold on to the component to be encapsulated (e.g., corners or holes in the pcb). And then a 2nd shot can cover up the areas that are used to hold the part in the 1st shot.

Do you already have the job to over-mold or is it development?

Is the project OEM or are you bidding on it?

Timeline to Launch

Equipment Section

Do you have a low pressure molding machine? If yes, please indicate model.

If you are planning to purchase a machine, do you require any safety modifications/certifications?

Material/Environmental Section

End environment
(e.g., outdoor, tire, office)?

Do you or your suppliers currently use low pressure molding or encapsulation? If so, please indicate what resin(s) are used.

If you know which material you want to use, please enter specifics. Otherwise, please answer questions below for a material recommendation.

Adhesion to pc board? If yes, please describe pcb.

Adhesion to wires? If yes, define wire jacket material?

Cable and other attachments?

Adhesion to other materials? If yes, which?

Maximum or minimum material thickness?

Service/Operating Temperature range
(i.e., min and max)?

Temperature cycle / shock requirements?

Exposure to water?
(e.g., immersion, humidity, salt fog or water)

Any solvents that the materials need to withstand?
(i.e., what fluids? Alcohol? Splashing? Immersion?)

UV exposure applicable? If yes, please explain.

UL certification required? If yes, please explain.

Vibration test requirements? If yes, please explain.

Other misc. testing the product will be subjected to? If yes, please explain.

Surface Preparation?

Color requirements? If yes, please explain.
(FYI - black & translucent amber are common. Other colors including optically clear are available.)

If you have any other project or product information or requirements now (or in the future), please add that here

FYI - this application sheet will be sent to LPMS Material Science Department and will be the basis for their material recommendation. Please attach pictures or reference pictures if relevant.

Signature

Date